Notes:
1. Current design is designed for maximum 1.1A constant current output, 100V~200V output voltage range.
2. One 2.1" x 1.25" x 0.125" heatsink is applied for D100, D102, Q100.
3. One 2.1" x 1.25" x 0.125" heatsink is applied for Q200, Q203.
4. Once PSON signal is switched high, it has to remain high until AC source removed.

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